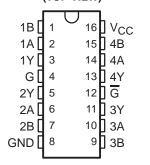
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- Meet or Exceed the Requirements of TIA/EIA-422-B, TIA/EIA-423-B, and TIA/EIA-485-A and ITU Recommendations V.10, V.11, X.26, and X.27
- **Designed for Multipoint Bus Transmission** on Long Bus Lines in Noisy Environments
- **3-State Outputs**
- Common-Mode Input Voltage Range of -12 V to 12 V
- Input Sensitivity . . . ±200 mV
- Input Hysteresis . . . 50 mV Typ
- High Input Impedance . . . 12 k Ω Min
- **Operate From Single 5-V Supply**
- **Low Power Requirements**
- Pin-to-Pin Replacement for AM26LS32

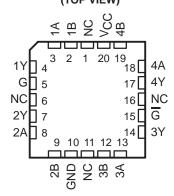
description

The SN55173, SN65173, and SN75173 are monolithic quadruple differential line receivers with 3-state outputs. They are designed to meet requirements of TIA/EIA-422-B, TIA/EIA-423-B, TIA/EIA-485-A, and several ITU recommendations. The standards are for balanced multipoint bus transmission at rates up to 10 megabits per second. The four receivers share two OR enable inputs, one active when high, the other active when low. These devices feature high input impedance, input hysteresis for increased noise immunity, and input sensitivity of ±200 mV over a common-mode input voltage range of –12 V to 12 V. Fail-safe design specifies that if the inputs are open circuited, the outputs are always high. The SN65173 and SN75173 are designed for optimum performance when used with the SN75172 or SN75174 quad differential line drivers.

SN55173...J PACKAGE **SN65173, SN75173...D OR N PACKAGE** (TOP VIEW)



SN55173 . . . FK PACKAGE (TOP VIEW)



NC-No internal connection

THE SN55173 IS NOT RECOMMENDED FOR NEW DESIGNS.

The SN55173 is characterized over the full military temperature range of -55°C to 125°C. The SN65173 is characterized for operation from -40 °C to 85 °C. The SN75173 is characterized for operation from 0 °C to 70 °C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



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AVAILABLE OPTIONS

		PACKAGED I	DEVICES	
TA	PLASTIC SMALL OUTLINE (D)	PLASTIC CHIP CARRIER (FK)	CERAMIC DIP	PLASTIC DIP (N)
0°C to 70°C	SN75173D	_	_	SN75173N
-40°C to 85°C	SN65173D	_	_	SN65173N
−55°C to 125°C	_	SN55173FK	SN55173J	_

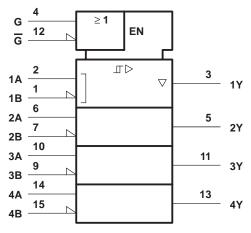
The D package is available taped and reeled. Add the suffix R to the device type (e.g., SN75173DR).

FUNCTION TABLE (each receiver)

DIFFERENTIAL	ENA	BLES	OUTPUT
A–B	G	G	Υ
V > 0.2 V	Н	Х	Н
V _{ID} ≥ 0.2 V	Х	L	Н
0.2 \/ 4 \/ 15 4 0.2 \/	Н	Х	?
$-0.2 \text{ V} < \text{V}_{1D} < 0.2 \text{ V}$	Х	L	?
V _{ID} ≤ -0.2 V	Н	Х	L
V D ≤ -0.2 V	Х	L	L
X	L	Н	Z
Open circuit	Х	L	Н
Open circuit	Н	X	Н

H = high level, L = low level, ? = indeterminate, X = irrelevant, Z = high impedance (off)

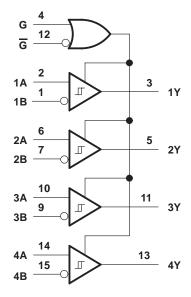
logic symbol †



 \dagger This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, and N packages.

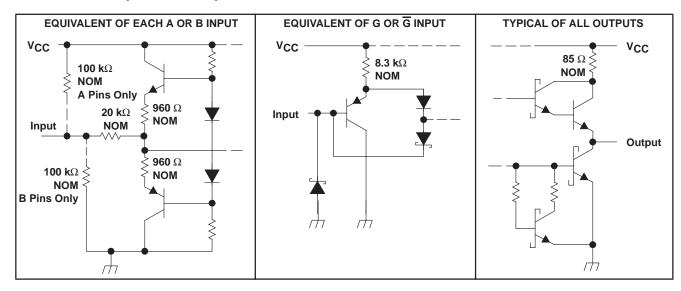


logic diagram (positive logic)



Pin numbers shown are for the D, J, and N packages.

schematics of inputs and outputs



SN55173, SN65173, SN75173 QUADRUPLE DIFFERENTIAL LINE RECEIVERS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)† Input voltage (V_I or B inputs)±25 V Differential input voltage, V_{ID} (see Note 2)±25 V Low-level output current, IOL 50 mA

- implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. NOTES: 1. All voltage values, except differential input voltage, are with respect to network ground terminal.
 - 2. Differential input voltage is measured at the noninverting input with respect to the corresponding inverting input.
 - 3. The package thermal impedance is calculated in accordance with JESD 51.

DISSIPATION RATING TABLE

PACKAGE	$T_{\mbox{\scriptsize A}} \le 25^{\circ}\mbox{\scriptsize C}$ POWER RATING	DERATING FACTOR	T _A = 70°C POWER RATING	T _A = 125°C POWER RATING
FK	1375 mW	11 mW/°C	880 mW	275 mW
J	1375 mW	11 mW/°C	880 mW	275 mW

recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage Vee	SN55173	4.5	5	5.5	V
Supply voltage, VCC	SN65173, SN75173	4.75	5	5.25	V
Common-mode input voltage, V _{IC}				±12	V
Differential input voltage, V _{ID}				±12	V
High-level enable-input voltage, VIH		2			V
Low-level enable-input voltage, V _{IL}				0.8	V
High-level output current, IOH				-400	μΑ
Low-level output current, IOL				16	mA
	SN55173	-55		125	
Operating free-air temperature, TA	SN65173	-40		85	°C
	SN75173	0		70	



Storage temperature range, T_{stq}-65°C to 150°C † Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not

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electrical characteristics over recommended ranges of common-mode input voltage, supply voltage, and operating free-air temperature

	PARAMETER	TES	T CONDITIONS		MIN	TYP [†]	MAX	UNIT
V _{IT+}	Positive-going input threshold voltage	$V_0 = 2.7 V$,	$I_{O} = -0.4 \text{ mA}$				0.2	V
V _{IT} _	Negative-going input threshold voltage	$V_0 = 0.5 V$,	I _O = 16 mA		-0.2‡			V
V _{hys}	Hysteresis (V _{IT+} – V _{IT} –)	See Figure 4				50		mV
VIK	Enable-input clamp voltage	I _I = -18 mA					-1.5	V
				SN55173	2.5			V
VOH	High-level output voltage	V _{ID} = 200 mV,	$I_{OH} = -400 \mu A$	SN65173, SN75173	2.7			V
V	Low level output voltage	\/ 200 m\/	Can Figure 4	$I_{OL} = 8 \text{ mA}$			0.45	V
VOL	Low-level output voltage	$V_{ID} = -200 \text{ mV},$	See Figure 1	I _{OL} = 16 mA			0.5	V
loz	High-impedance-state output current	$V_0 = 0.4 \text{ V to } 2.4 \text{ V}$					±20	μΑ
1.	Line input current	Other input at 0 V,	See Note 3	V _I = 12 V			1	mA
ا ^ا	Line input current	Other input at 0 v,	See Note 3	V _I = −7 V			-0.8	IIIA
lн	High-level enable-input current	V _{IH} = 2.7 V	V _{IH} = 2.7 V				20	μΑ
I _{IL}	Low-level enable-input current	V _{IL} = 0.4 V					-100	μΑ
rį	Input resistance				12			kΩ
los	Short-circuit output current				-15		-85	mA
ICC	Supply current	Outputs disabled					70	mA

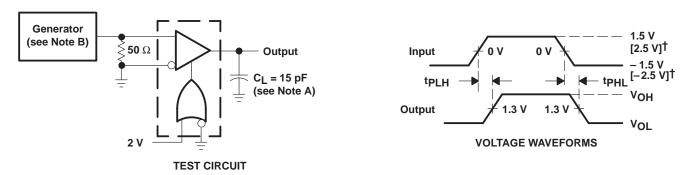
NOTE 3: Refer to TIA/EIA-422-B and TIA/EIA-423-B for exact conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST CO	NDITIONS	MIN	TYP	MAX	UNIT
tPLH	Propagation delay time, low-to-high-level output	V _{ID} = -1.5 V	to 1.5 V,		20	35	ns
tPHL	Propagation delay time, high-to-low-level output	$C_L = 15 pF$,	See Figure 1		22	35	ns
tPZH	Output enable time to high level	$C_L = 15 pF$,	See Figure 2		17	22	ns
tpzL	Output enable time to low level	$C_L = 15 pF$,	See Figure 3		20	25	ns
tPHZ	Output disable time from high level	$C_L = 5 pF$,	See Figure 2		21	30	ns
tPLZ	Output disable time from low level	$C_L = 5 pF$,	See Figure 3		30	40	ns

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C. ‡ The algebraic convention, in which the less positive (more negative) limit is designated as minimum, is used in this data sheet for threshold voltage levels only.

PARAMETER MEASUREMENT INFORMATION

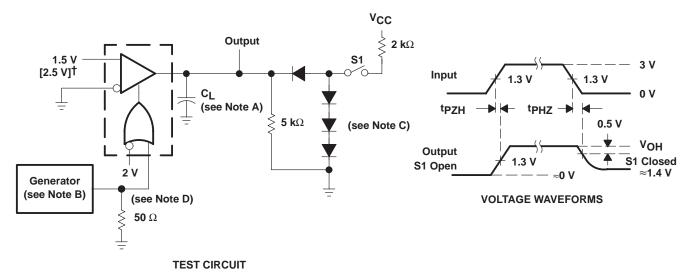


[†] Voltage for the SN55173 only.

NOTES: A. C_L includes probe and jig capacitance.

B. The input pulse is supplied by a generator having the following characteristics: PRR = 1 MHz, duty cycle = 50%, $t_{\Gamma} \le 6$ ns, $t_{\Gamma} \le 6$

Figure 1. tplH, tpHL Test Circuit and Voltage Waveforms



† Voltage for the SN55173 only.

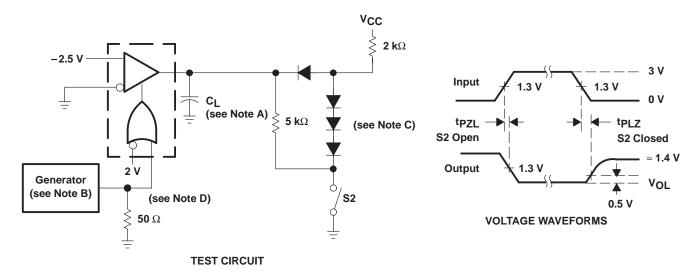
NOTES: A. C_L includes probe and jig capacitance.

- B. The input pulse is supplied by a generator having the following characteristics: PRR = 1 MHz, duty cycle = 50%, $t_r \le 6$ ns, $t_f \le 6$ ns
- C. All diodes are 1N916, or equivalent.
- D. To test the active-low enable \overline{G} , ground G and apply an inverted input waveform to \overline{G} .

Figure 2. t_{PHZ}, t_{PZH} Test Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION

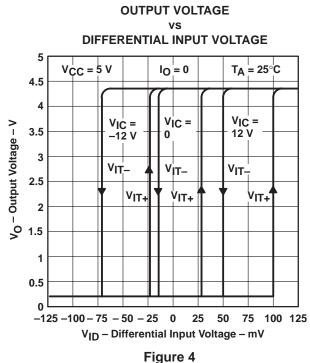


NOTES: A. C_L includes probe and jig capacitance.

- B. The input pulse is supplied by a generator having the following characteristics: PRR = 1 MHz, duty cycle = 50%, $t_f \le 6$ ns, $t_f \le 6$ ns
- C. All diodes are 1N916, or equivalent.
- D. To test the active-low enable \overline{G} , ground G and apply an inverted input waveform to \overline{G} .

Figure 3. tpzl, tpLZ Test Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS[†]



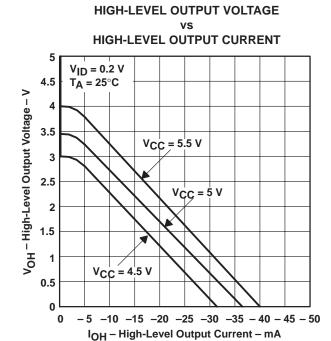
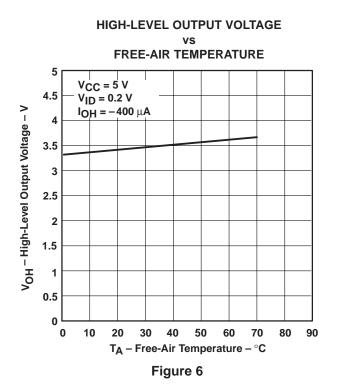


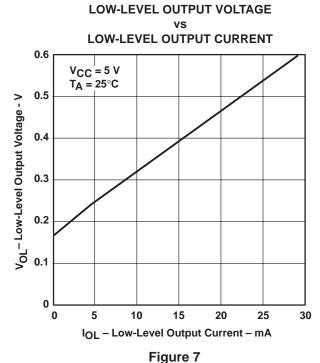
Figure 5

[†] Operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.

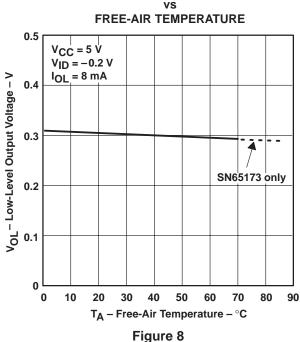


TYPICAL CHARACTERISTICS†

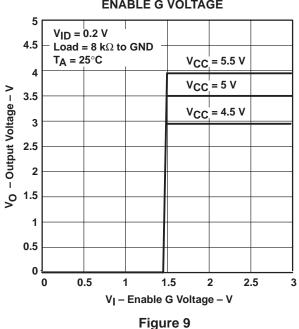




LOW-LEVEL OUTPUT VOLTAGE
vs
FREE-AIR TEMPERATURE



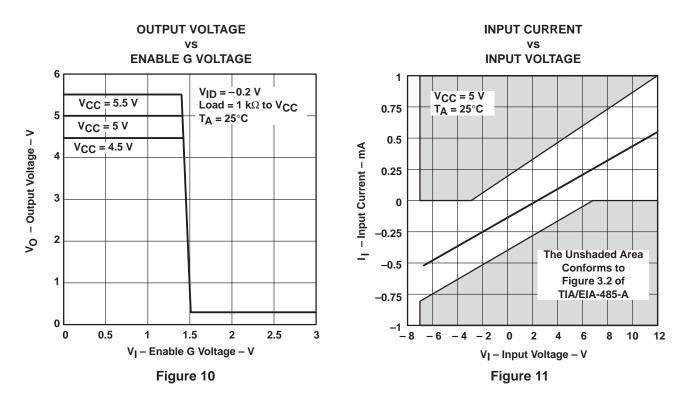
OUTPUT VOLTAGE vs ENABLE G VOLTAGE



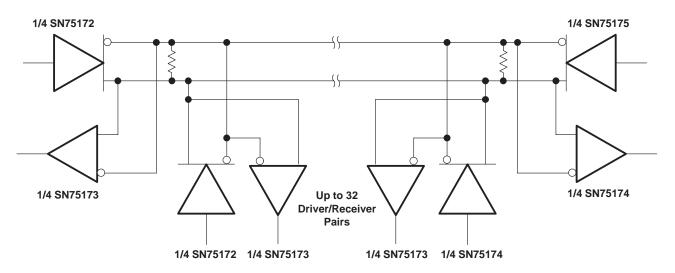
[†] Operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.



TYPICAL CHARACTERISTICS



APPLICATION INFORMATION



NOTE A: The line should be terminated at both ends in its characteristic impedance. Stub lengths off the main line should be kept as short as possible.

Figure 12. Typical Application Circuit



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microcontroller.ti.com	Security	www.ti.com/security
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	Wireless	www.ti.com/wireless
	dataconverter.ti.com dsp.ti.com interface.ti.com logic.ti.com power.ti.com microcontroller.ti.com	amplifier.ti.com dataconverter.ti.com dsp.ti.com dsp.ti.com interface.ti.com logic.ti.com power.ti.com microcontroller.ti.com www.ti.com/lpw Audio Audio Audio Audio Automotive Broadband Digital Control Military Optical Networking Security Telephony Video & Imaging

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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp (3)
SN55173J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN65173D	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI
SN65173DR	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI
SN65173N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN75173D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75173DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75173DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75173DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75173DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75173DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75173J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SN75173N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75173NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75173NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75173NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75173NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ55173FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ55173J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



PACKAGE OPTION ADDENDUM

9-Oct-2007

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device		Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75173DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN75173NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75173DR	SOIC	D	16	2500	333.2	345.9	28.6
SN75173NSR	SO	NS	16	2000	346.0	346.0	33.0

FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AC.



D(R-PDSO-G16)



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Refer to IPC7351 for alternate board design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC—7525
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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